



Field tested, fail-safe and long life performance in extreme conditions. Feature-rich Crystal Group sealed embedded computer systems are powerful, compact and rugged. Easily configurable to meet specific customer requirements, the embedded product line boasts advanced thermal management and all-aluminum chassis field tested to withstand shock and vibration, extended temperature ranges, harsh elements and extreme environments. Crystal Group sealed embedded computer systems follow the Intel® embedded roadmap to ensure access to the latest in long life, powerful Intel chipsets and processors.

Innovative solutions. Crystal Group's portfolio of rugged and industrial computing products are engineered and tested to withstand challenging environments, meet and exceed military and industrial standards, and provide the latest COTS technologies to best manage cost, availability, scalability and flexibility.

Dependable services. When a computing application requires a custom solution, Crystal Group delivers with vertically-integrated services, including product design and development, testing, systems engineering and integration, mechanical and electrical engineering, configuration management, and product life-cycle planning.

Dedicated support. Crystal Group's expert staff and global network provide fast and effective product support when and where it is needed. Count on Crystal Group for prompt response times, quick turnarounds, 5+ year warranties, and quality service around the clock and around the globe.

FEATURES

- All-aluminum construction – 23 lbs.
- Easily mounted from base or top
- Rugged sealed system rated to IP67
- Versatility with up to six 2.5" SSD hard drives
- Power efficient Broadwell DE/ Xeon-D
- Natural convection cooled, does not require cold plate

A clear advantage.

Specifications

Mechanical

Height: 13.34" (33.9cm)
 Width: 3.7" (9.4 cm) max
 Depth: 14.075" (35.8 cm) over body, 16.275" (42.5cm) max over handles & MIL-CIRC connectors
 Weight: 23 lbs. (10.5 kg) max with all drives populated and one card installed

CPU

Intel® CPU architecture options from Intel embedded long-life roadmap
 Six core , X10SDV-6C

Internal Expansion Slots

One PCIeX16 3/4 length 8.5" max height

Removable Drives & I/O

Option 1: Six removable 2.5" drives
 Option 2: Three removable drives & capacitance holdup module
 Option 3: Rotational hard drives with reduced vibration or temperature specifications
 Option 4: Above options with easy access thumb screws for drive access door (not IP67 compliant)

Mounting

Mounted from base flanges with eight 12-24 socket head machine screws

System Board

X10SDV-6C

Environmental Standards

MIL-STD-810, Operational Temperature, Method 501, Procedure I/II: -40°C to +50°C, reduced performance to +71°C¹
 MIL-STD-810, Storage, Method 501, Procedure I/II: -55°C to +85°C¹
 MIL-STD-810, Humidity, Method 507, Procedure II: 240 hours²
 MIL-STD-810, Altitude, Method 500: 12,500ft operation, 40,000ft transport²
 MIL-901, Grade B, Class 2, Type B: Testing performed with SSD²
 MIL-STD-810, Vibration, Method 514, Procedure I: 5.5G, 10-2,000Hz, 60 min/axis, 3 axis with vibration kit²

Electromagnetic Compatibility Standards

Some standards may require an internal kit
 DC, MIL-STD-461, RE102, CE102 compliant²

Cooling

Natural convection, requires 1.5" clearance (side to side) for full thermal performance

Software Compatibility

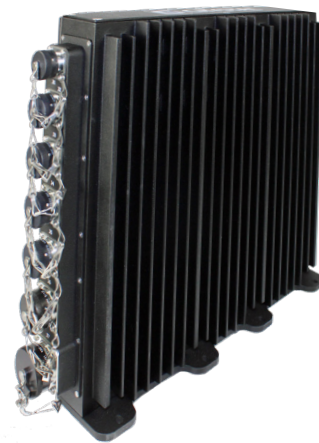
Supports Windows® 10, Linux® , or VMware®

Internal Bay

Single SATA 2.5" SSD (externally removable) and single internal M.2 SSD

Power Supply

18-36VDC MIL-STD-1275, MIL-STD-704, MIL-STD-461



1 - Test report available
 2 - Designed to meet standard

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